

LIQUID SOLDER THERMAL INTERFACE MATERIAL  
CONTAINED WITHIN A COLD-FORMED BARRIER  
AND METHODS OF MAKING SAME

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ABSTRACT OF THE DISCLOSURE

In a process of making a container barrier upon a heat spreader, the heat spreader is augmented with a cold-formed o-ring, and thereafter, it is bonded to a die. A liquid solder is filled into the space created by the o-ring. The thermal interface material can also have one of several footprints to facilitate heat transfer.

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